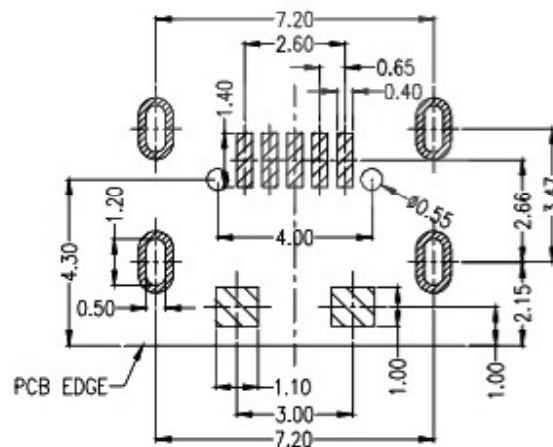
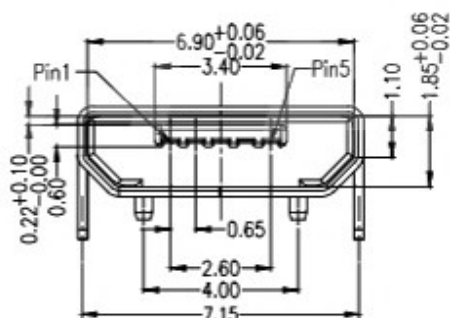
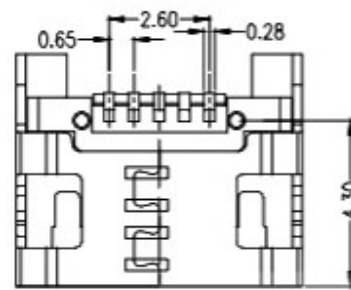
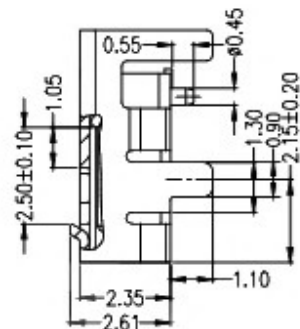
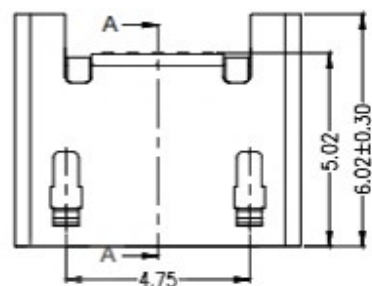


SECTION A-A



RECOMMENDED PCB LAYOUT
PCB图仅供参考

Note:

1.Material:

- 1.1 Housing: High temperature thermoplastic with g.f,UL94v-0
- 1.2 Contact: copper alloy,t=0.20mm
- 1.3 Shell: copper alloy,t=0.25mm

2.Specification:

- 2.1 Current rating: 1 A Max.
- 2.2 Dielectric withstanding voltage: 100 V(ac) for 1 min.
- 2.3 Contact resistance: 30 mΩ Max.
- 2.4 Insulation resistance: 100 MΩ Min.
- 2.5 Total mating force: 3.57 Kgf Max.
- 2.6 Total unmating force: 1.0 Kgf Min.
- 2.7 Temperature range: -30°C~80°C

3. FINISH

- CONTACT: 50U" MIN NICKEL UNDERPLATING OVERALL GOLD PLATING SELECTIVE ON CONTACT AREA 50U" MIN TIN PLATING ON SOLDER TAIL
- SHELL: 40U" MIN NICKEL UNDERPLATING OVERALL

PART NAME		CONNECTOR			DRAWING	Y,C,ZHANG	DWG.No.	SBICL
PART NO.		Micro usb 5P/PF B Type插板7.2有柱脚长1.1四脚全插平口			CHECK	G.C.Chen	REV.	A1
UNIT : mm	TOLERANCE OTHERWISE	UP TO 5	±0.2	ANGLE	APPROVAL	DATE	PAGE	1 OF 1
		ABOVE 5~30	±0.3					
		ABOVE 30	±0.5	0±5	SCALE	2:1		